

# Automotive Dual N-Channel 40 V (D-S) 175 °C MOSFET

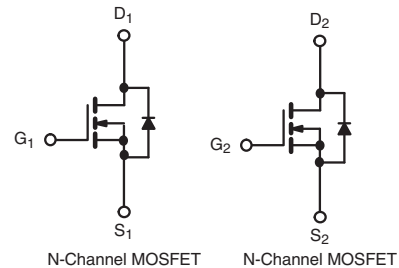
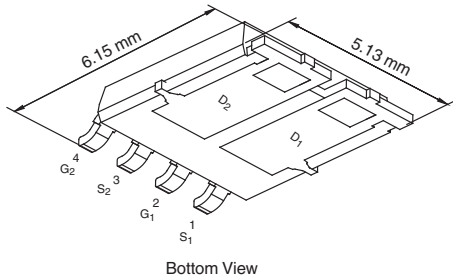


PRODUCT SUMMARY	
$V_{DS}$ (V)	40
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 10$ V	0.014
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 4.5$ V	0.015
$I_D$ (A) per leg	8
Configuration	Dual

## FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 %  $R_g$  and UIS Tested
- Compliant to RoHS Directive 2002/95/EC
- AEC-Q101 Qualified<sup>d</sup>

PowerPAK® SO-8L Dual



ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SQJ912EP-T1-GE3

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		$V_{DS}$	40	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	
Continuous Drain Current <sup>a</sup>	$T_C = 25$ °C	$I_D$	8	A
	$T_C = 125$ °C		8	
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	8	
Pulsed Drain Current <sup>b</sup>		$I_{DM}$	32	
Single Pulse Avalanche Current	L = 0.1 mH	$I_{AS}$	33	
Single Pulse Avalanche Energy		$E_{AS}$	56	
Maximum Power Dissipation <sup>b</sup>	$T_C = 25$ °C	$P_D$	48	W
	$T_C = 125$ °C		16	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature) <sup>e, f</sup>			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>c</sup>	$R_{thJA}$	85	°C/W
Junction-to-Case (Drain)		$R_{thJC}$	3.1	

### Notes

- Package limited.
- Pulse test; pulse width  $\leq 300$   $\mu$ s, duty cycle  $\leq 2$  %.
- When mounted on 1" square PCB (FR4 material).
- Parametric verification ongoing.
- See solder profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257)). The PowerPAK SO-8L. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection..
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



<b>SPECIFICATIONS</b> ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	40	-	-	V
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1.3	1.8	2.3	
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}$ $V_{DS} = 40\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ $V_{DS} = 40\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	50	
		$V_{GS} = 0\text{ V}$ $V_{DS} = 40\text{ V}, T_J = 175\text{ }^\circ\text{C}$	-	-	150	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{GS} = 10\text{ V}$ $V_{DS} \geq 5\text{ V}$	30	-	-	A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ $I_D = 11\text{ A}$	-	0.011	0.014	$\Omega$
		$V_{GS} = 4.5\text{ V}$ $I_D = 8\text{ A}$	-	0.012	0.015	
		$V_{GS} = 10\text{ V}$ $I_D = 11\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	-	0.021	
		$V_{GS} = 10\text{ V}$ $I_D = 11\text{ A}, T_J = 175\text{ }^\circ\text{C}$	-	-	0.025	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 10\text{ A}$	-	44	-	S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$ $V_{DS} = 20\text{ V}, f = 1\text{ MHz}$	-	1799	2248	$\mu\text{F}$
Output Capacitance	$C_{oss}$		-	282	352	
Reverse Transfer Capacitance	$C_{rss}$		-	109	136	
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{GS} = 10\text{ V}$ $V_{DS} = 20\text{ V}, I_D = 11.3\text{ A}$	-	31.5	48	nC
Gate-Source Charge <sup>c</sup>	$Q_{gs}$		-	5.7	-	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$		-	4.8	-	
Gate Resistance	$R_g$	$f = 1\text{ MHz}$	2.1	4.3	7	$\Omega$
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = 20\text{ V}, R_L = 1.77\text{ }\Omega$ $I_D \cong 11.3\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$	-	7	11	ns
Rise Time <sup>c</sup>	$t_r$		-	21	32	
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$		-	33	50	
Fall Time <sup>c</sup>	$t_f$		-	19	29	
<b>Source-Drain Diode Ratings and Characteristics<sup>b</sup></b>						
Pulsed Current <sup>a</sup>	$I_{SM}$		-	-	32	A
Forward Voltage	$V_{SD}$	$I_F = 8\text{ A}, V_{GS} = 0\text{ V}$	-	0.8	1.1	V

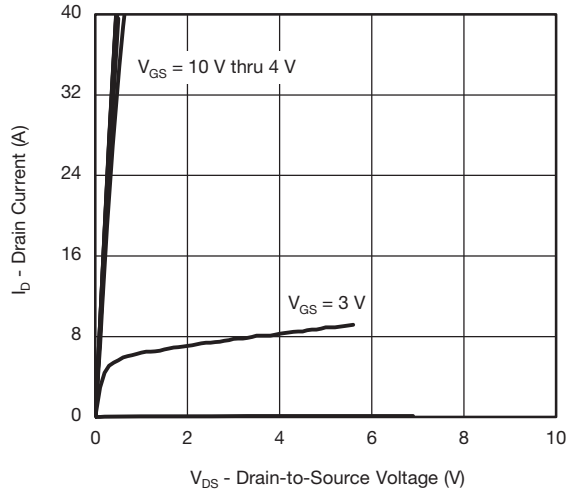
**Notes**

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

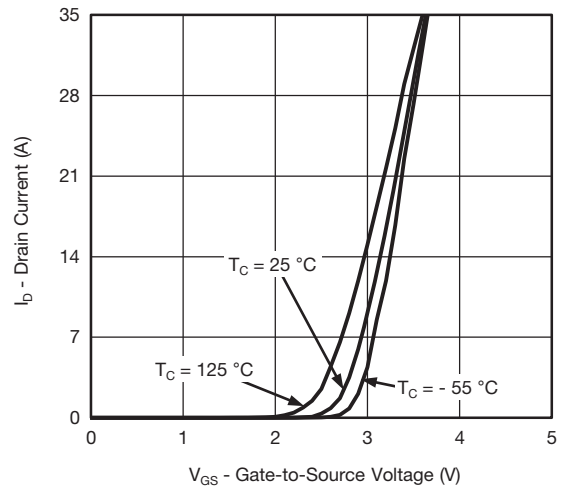
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



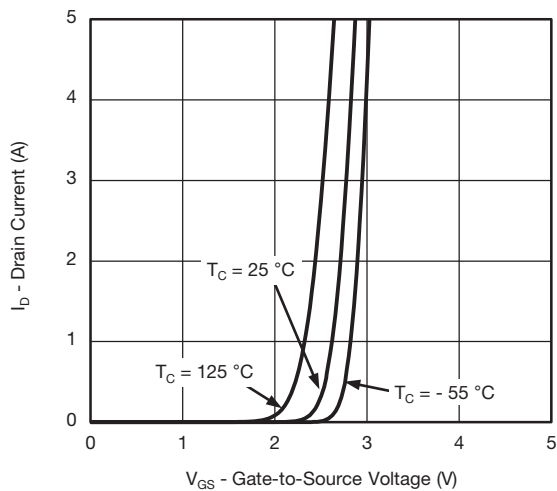
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



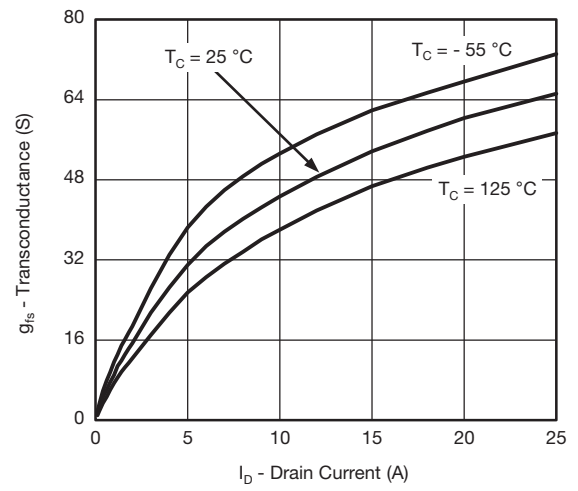
Output Characteristics



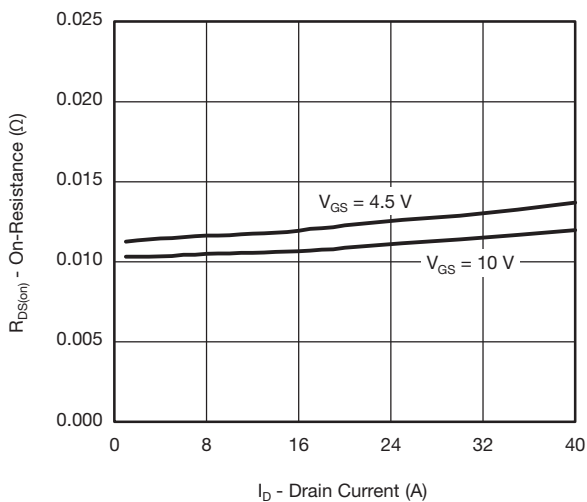
Transfer Characteristics



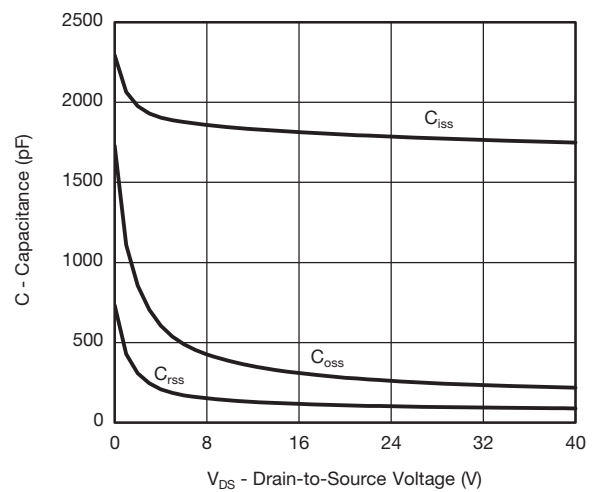
Transfer Characteristics



Transconductance



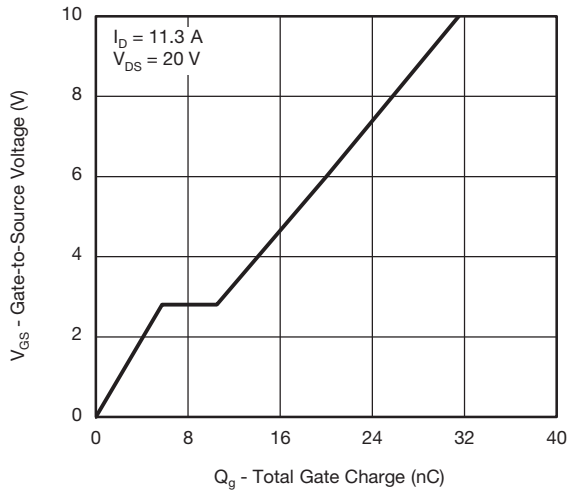
Capacitance



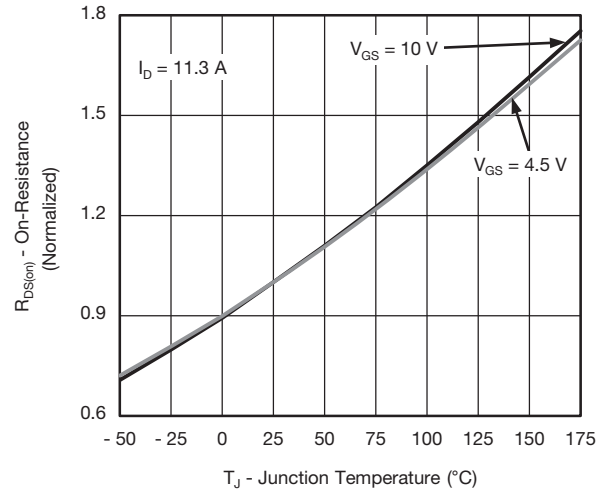
Gate Charge



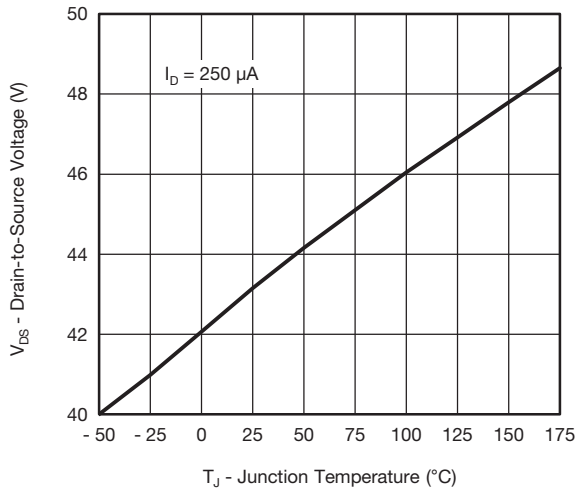
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



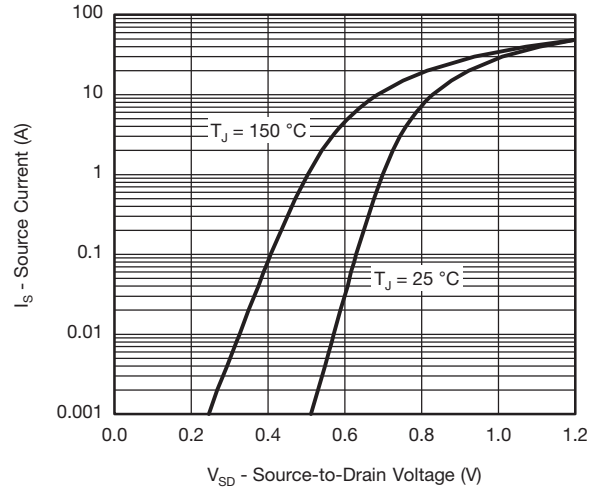
**On-Resistance vs. Drain Current**



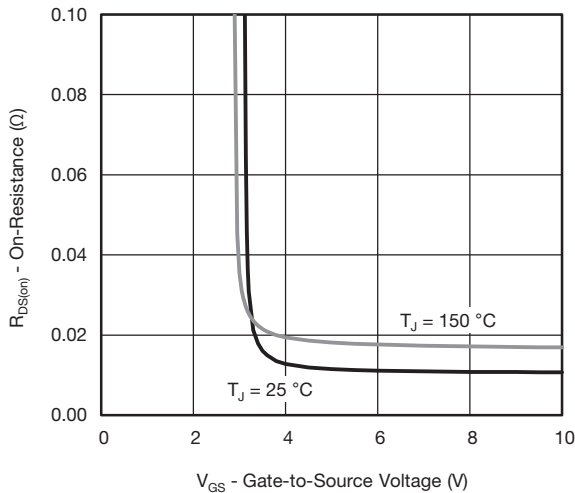
**Drain-Source Breakdown vs. Junction Temperature**



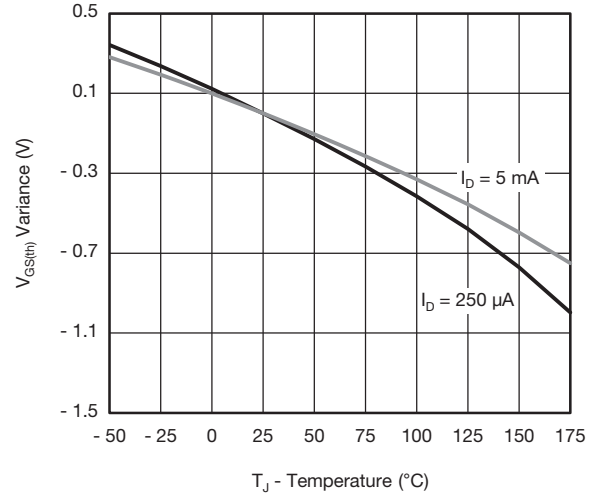
**Source Drain Diode Forward Voltage**



**On-Resistance vs. Gate-to-Source Voltage**

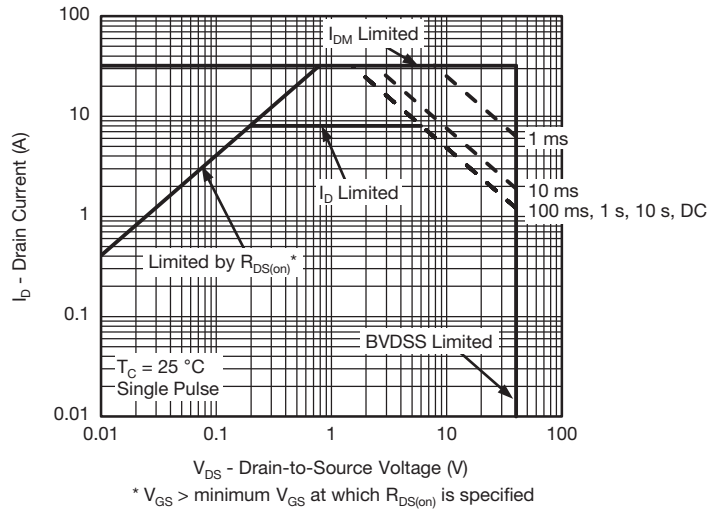


**On-Resistance vs. Junction Temperature**

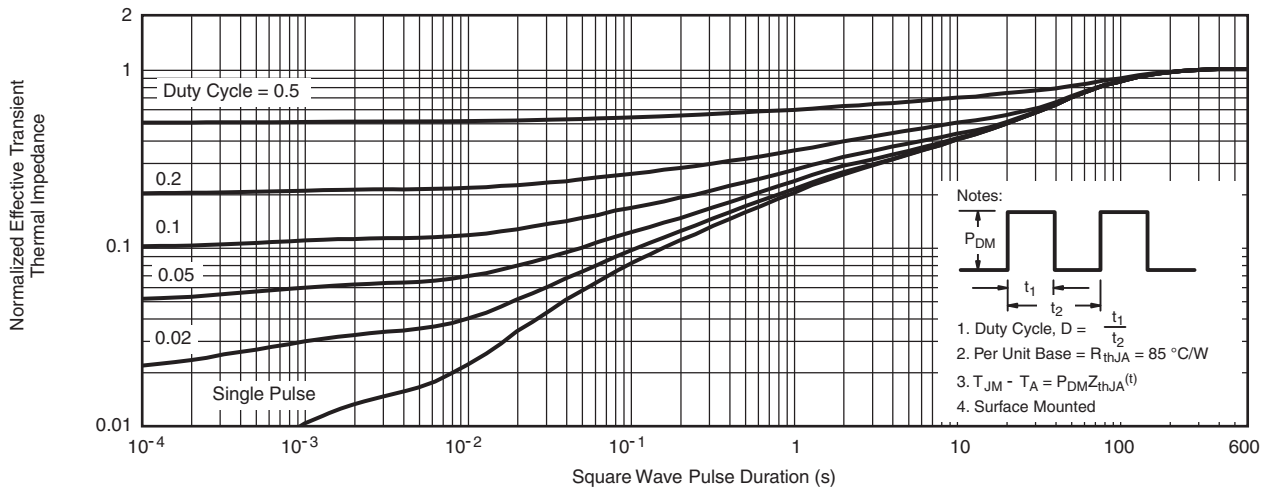


**Threshold Voltage**

**THERMAL RATINGS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



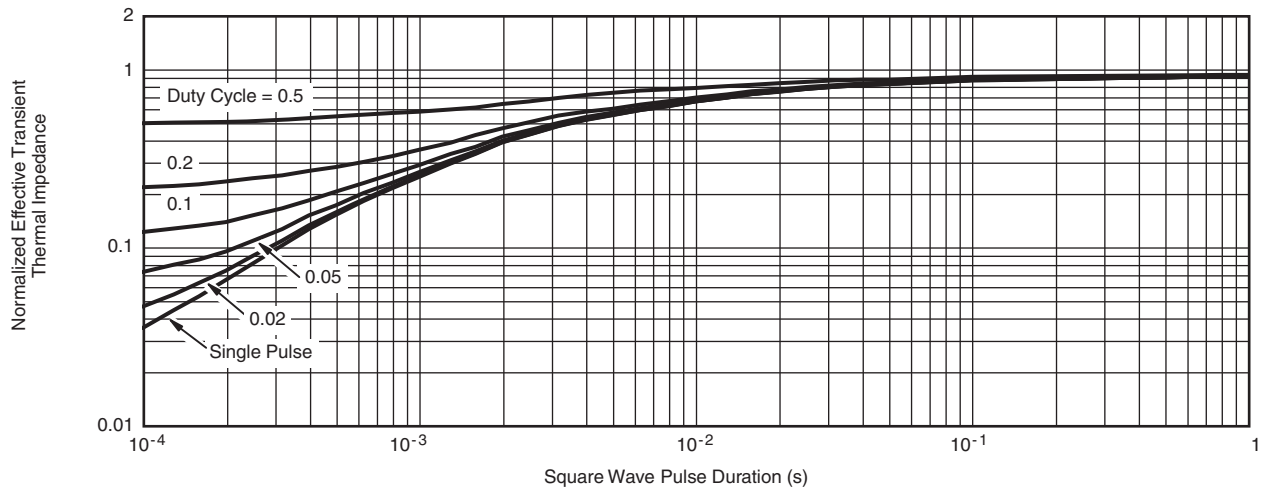
**Safe Operating Area**



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**THERMAL RATINGS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Case**

**Note**

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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